

Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

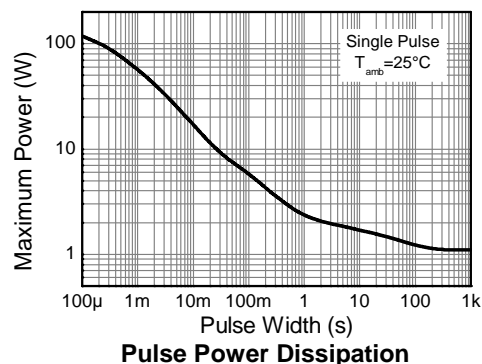
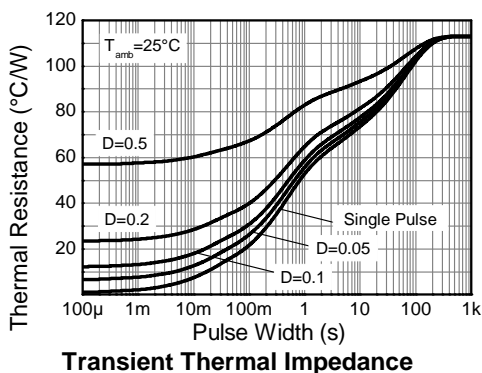
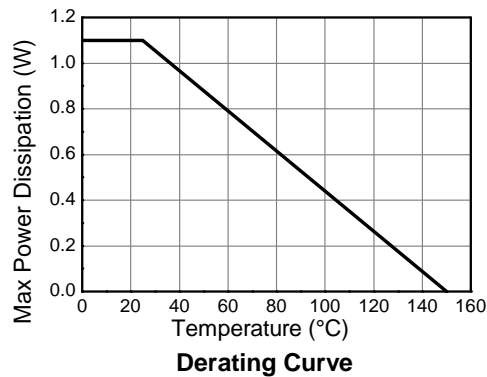
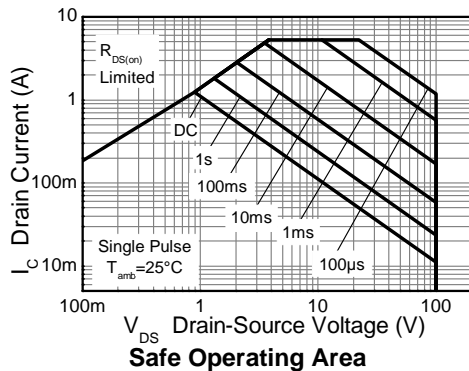
Characteristic			Symbol	Value	Unit
Drain-Source Voltage			V _{DSS}	100	V
Gate-Source Voltage			V _{GS}	±20	V
Continuous Drain Current	V _{GS} = 10V	Note 5)	I _D	1.9	A
		T _A =+70°C (Note 5)		1.5	
		(Note 4)		1.5	
		(Note 7)		3.5	
Pulsed Drain Current		(Note 6)	I _{DM}	8.6	A
Continuous Source Current (Body Diode)		(Note 5)	I _S	2.5	A
Pulsed Source Current (Body Diode)		(Note 6)	I _{SM}	8.6	A

Thermal Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic		Symbol	Value	Unit
Power Dissipation	(Note 4)	P _D	1.1	W
	(Note 5)		1.7	
	(Note 7)		6.3	
Thermal Resistance, Junction to Ambient	(Note 4)	R _{θJA}	114	°C/W
	(Note 5)		73.5	
Thermal Resistance, Junction to Leads	(Note 7)	R _{θJL}	19.7	°C/W
Operating and Storage Temperature Range		T _J , T _{STG}	-55 to +150	°C

- Notes:
4. For a device surface mounted on 25mm x 25mm FR4 PCB with high coverage of single sided 1oz copper, in still air conditions.
 5. For a device surface mounted on FR4 PCB measured at t ≤ 5 sec.
 6. Repetitive rating 25mm x 25mm FR4 PCB, D = 0.02, pulse width 300μs - pulse width limited by maximum junction temperature.
 7. Thermal resistance from junction to solder-point (at the end of the drain lead).

Thermal Characteristics

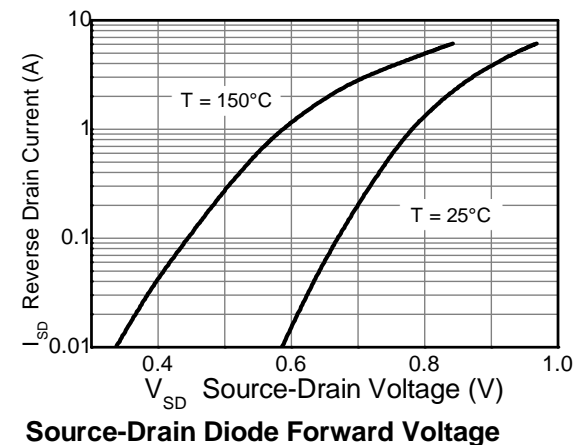
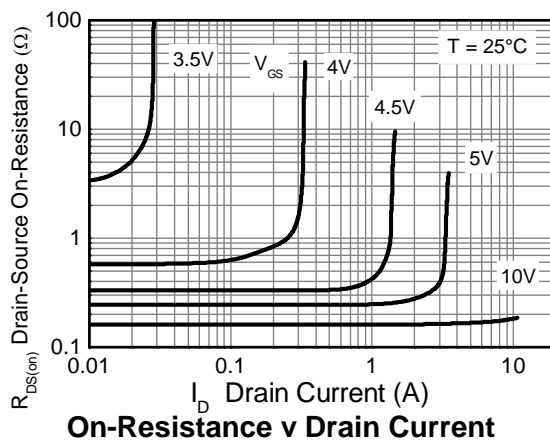
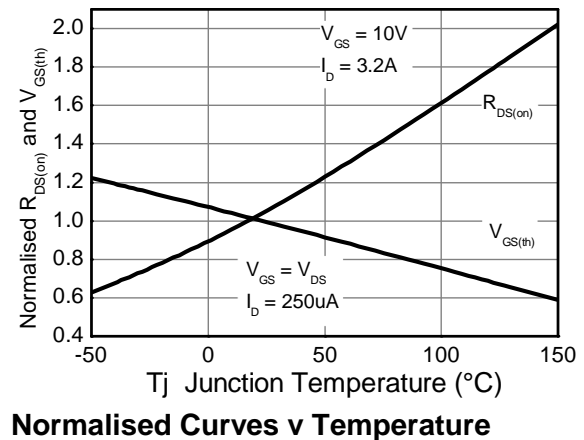
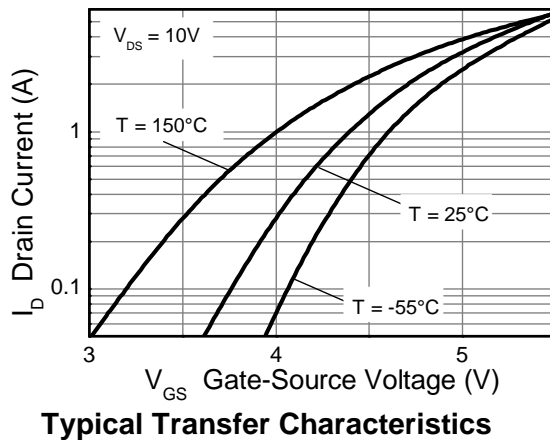
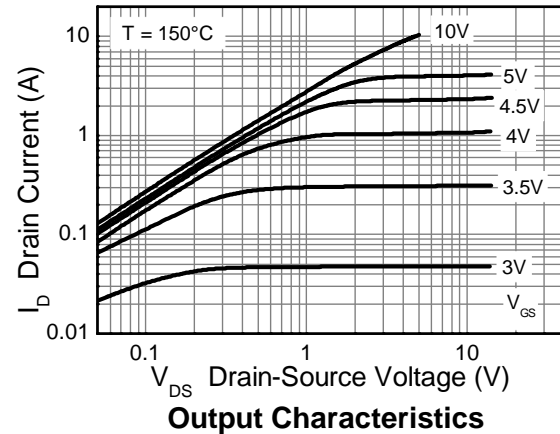
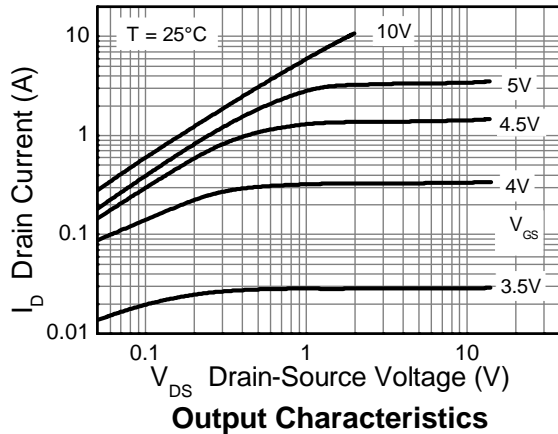


Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

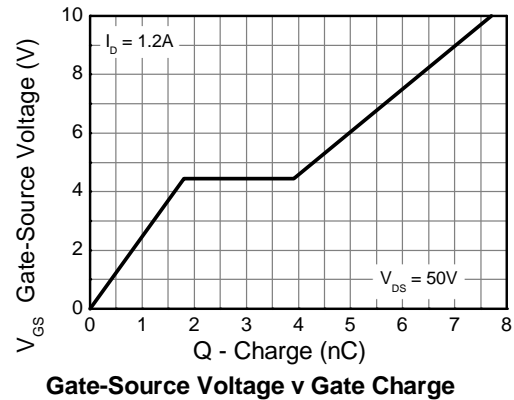
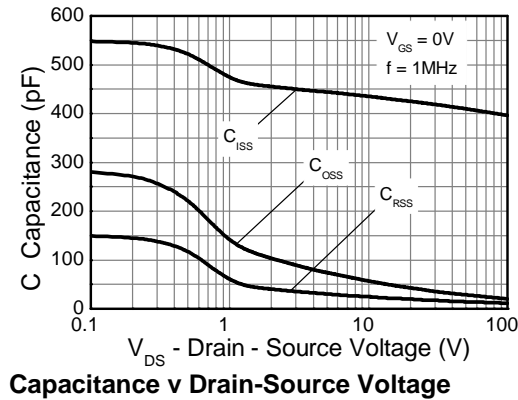
Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
OFF CHARACTERISTICS						
Drain-Source Breakdown Voltage	BV _{DSS}	100	—	—	V	I _D = 250μA, V _{GS} = 0V
Zero Gate Voltage Drain Current	I _{DSS}	—	—	0.5	μA	V _{DS} = 100V, V _{GS} = 0V
Gate-Source Leakage	I _{GSS}	—	—	100	nA	V _{GS} = ±20V, V _{DS} = 0V
ON CHARACTERISTICS						
Gate Threshold Voltage	V _{GS(th)}	2.0	—	4.0	V	I _D = 250μA, V _{DS} = V _{GS}
Static Drain-Source On-Resistance (Note 8)	R _{DS (ON)}	—	—	0.25	Ω	V _{GS} = 10V, I _D = 3.2A
				0.30		V _{GS} = 6V, I _D = 2.6A
Forward Transconductance (Notes 8 & 10)	g _{fs}	—	5.0	—	S	V _{DS} = 15V, I _D = 3.2A
Diode Forward Voltage (Note 8)	V _{SD}	—	0.87	0.95	V	I _S = 3.2A, V _{GS} = 0V
Reverse Recovery Time (Note 10)	t _{rr}	—	27	—	ns	I _S = 1.2A, di/dt = 100A/μs
Reverse Recovery Charge (Note 10)	Q _{rr}	—	32	—	nC	
DYNAMIC CHARACTERISTICS (Note 10)						
Input Capacitance	C _{iss}	—	405	—	pF	V _{DS} = 50V, V _{GS} = 0V f = 1MHz
Output Capacitance	C _{oss}	—	28.2	—	pF	
Reverse Transfer Capacitance	C _{rss}	—	14.2	—	pF	
Gate Charge (Note 9)	Q _g	—	4.2	—	nC	V _{GS} = 5V, V _{DS} = 50V I _D = 1.2A
Total Gate Charge (Note 9)	Q _g	—	7.7	—	nC	V _{GS} = 10V, V _{DS} = 50V I _D = 1.2A
Gate-Source Charge (Note 9)	Q _{gs}	—	1.8	—	nC	
Gate-Drain Charge (Note 9)	Q _{gd}	—	2.1	—	nC	
Turn-On Delay Time (Note 9)	t _{d(on)}	—	3.4	—	ns	V _{DD} = 30V, V _{GS} = 10V I _D = 1.2A, R _G ≐ 6.0Ω
Turn-On Rise Time (Note 9)	t _r	—	2.2	—	ns	
Turn-Off Delay Time (Note 9)	t _{d(off)}	—	8	—	ns	
Turn-Off Fall Time (Note 9)	t _f	—	3.2	—	ns	

Notes: 8. Measured under pulsed conditions. Width ≤300μs. Duty cycle ≤2%.
9. Switching characteristics are independent of operating junction temperature.
10. For design aid only, not subject to production testing.

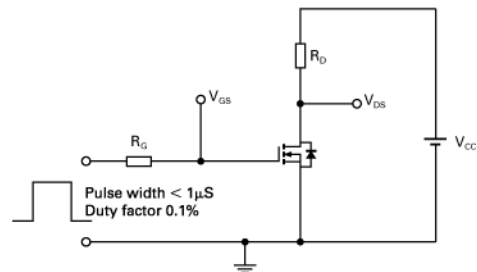
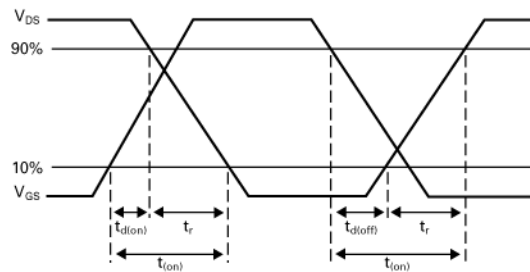
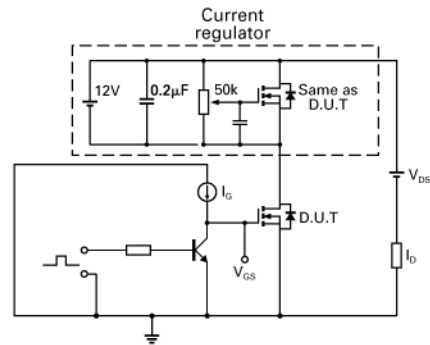
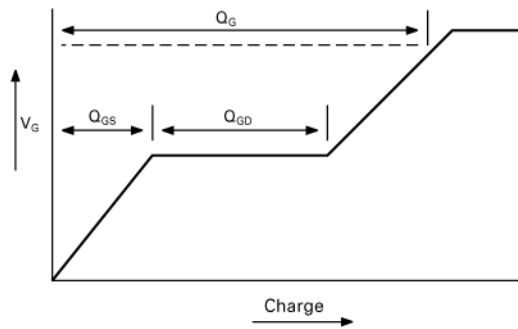
Typical Characteristics



Typical Characteristics (continued)

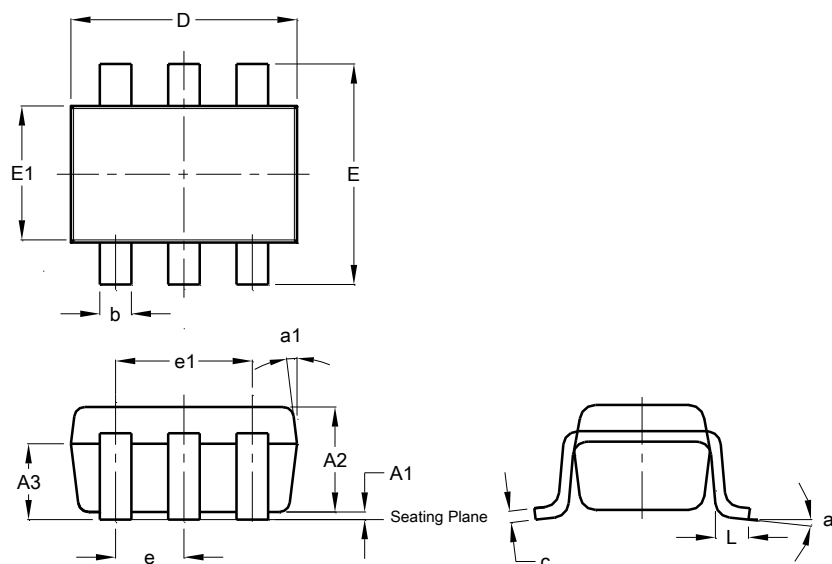


Test Circuits



Package Outline Dimensions

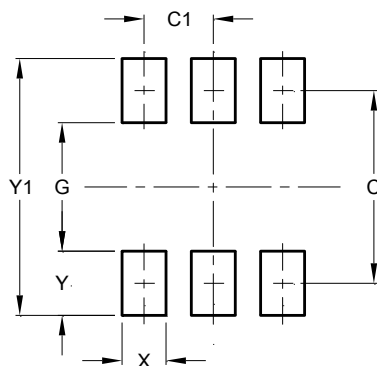
Please see AP02002 at <http://www.diodes.com/datasheets/ap02002.pdf> for the latest version.



SOT26			
Dim	Min	Max	Typ
A1	0.013	0.10	0.05
A2	1.00	1.30	1.10
A3	0.70	0.80	0.75
b	0.35	0.50	0.38
c	0.10	0.20	0.15
D	2.90	3.10	3.00
e	-	-	0.95
e1	-	-	1.90
E	2.70	3.00	2.80
E1	1.50	1.70	1.60
L	0.35	0.55	0.40
a	-	-	8°
a1	-	-	7°
All Dimensions in mm			

Suggested Pad Layout

Please see AP02001 at <http://www.diodes.com/datasheets/ap02001.pdf> for the latest version.



Dimensions	Value (in mm)
C	2.40
C1	0.95
G	1.60
X	0.55
Y	0.80
Y1	3.20

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